

# 2SK3150(L), 2SK3150(S)

Silicon N Channel MOS FET  
High Speed Power Switching

# HITACHI

ADE-208-750A (Z)

2nd. Edition

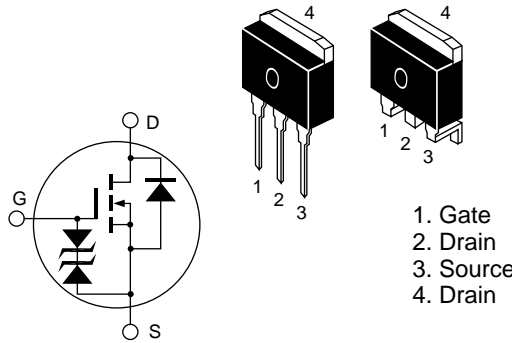
February 1999

## Features

- Low on-resistance  
 $R_{DS} = 45 \text{ m}\Omega$  typ.
- High speed switching
- 4 V gate drive device can be driven from 5 V source

## Outline

LDPAK



# 2SK3150(L),2SK3150(S)

## Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	100	V
Gate to source voltage	$V_{GSS}$	$\pm 20$	V
Drain current	$I_D$	20	A
Drain peak current	$I_{D(pulse)}$ <sup>Note1</sup>	60	A
Body-drain diode reverse drain current	$I_{DR}$	20	A
Avalanche current	$I_{AP}$ <sup>Note3</sup>	20	A
Avalanche energy	$E_{AR}$ <sup>Note3</sup>	40	mJ
Channel dissipation	$P_{ch}$ <sup>Note2</sup>	50	W
Channel temperature	$T_{ch}$	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

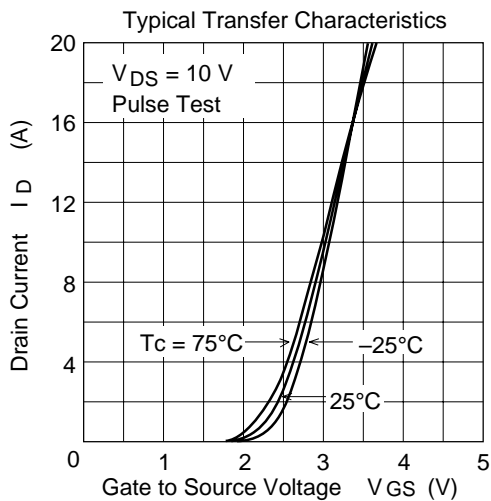
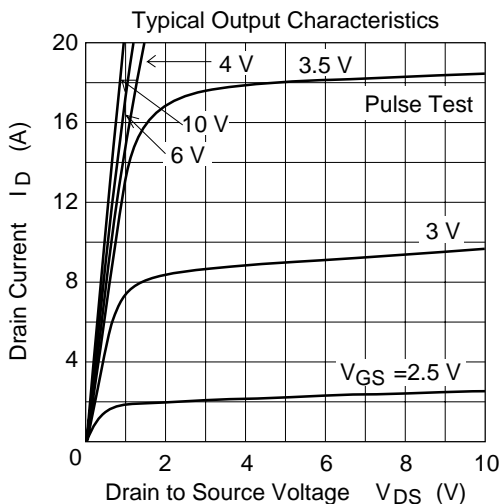
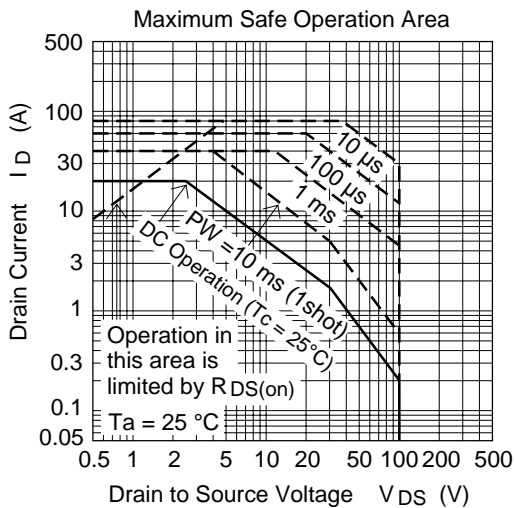
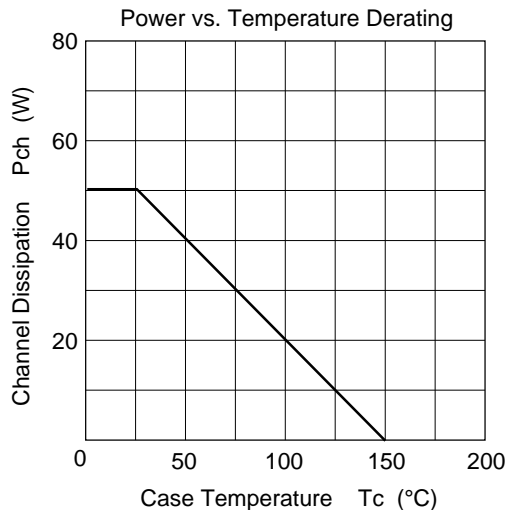
- Note: 1.  $PW \leq 10 \mu s$ , duty cycle  $\leq 1\%$   
 2. Value at  $T_c = 25^\circ C$   
 3. Value at  $T_{ch} = 25^\circ C$ ,  $R_g \geq 50 \Omega$

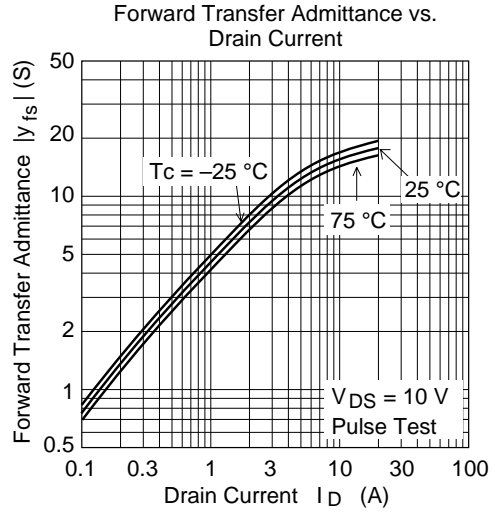
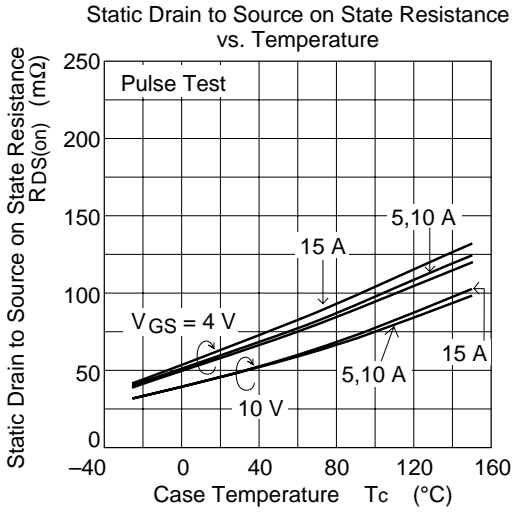
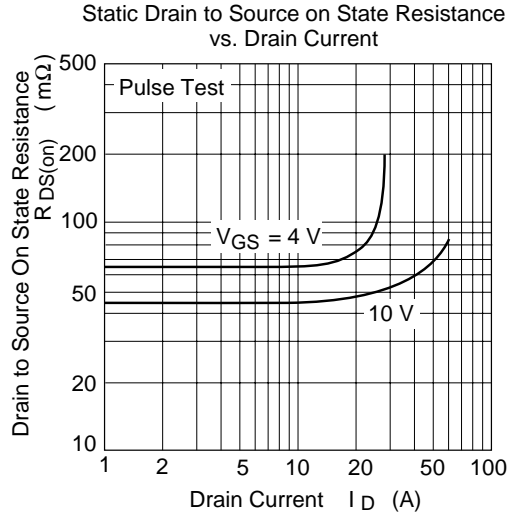
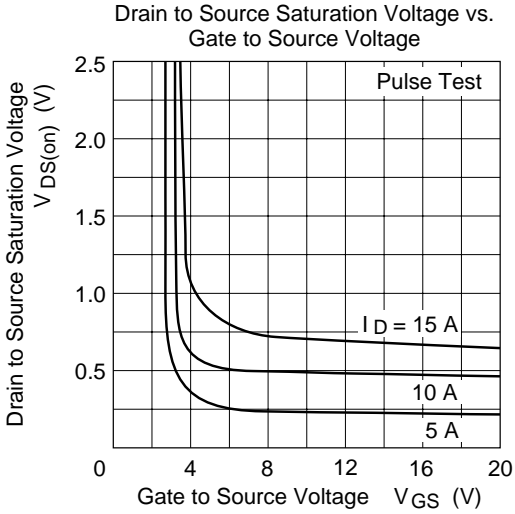
## Electrical Characteristics (Ta = 25°C)

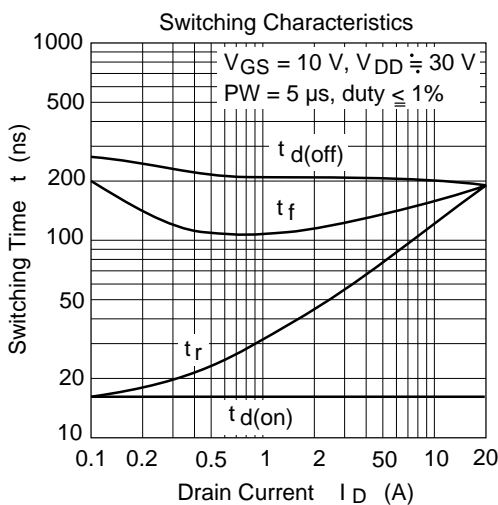
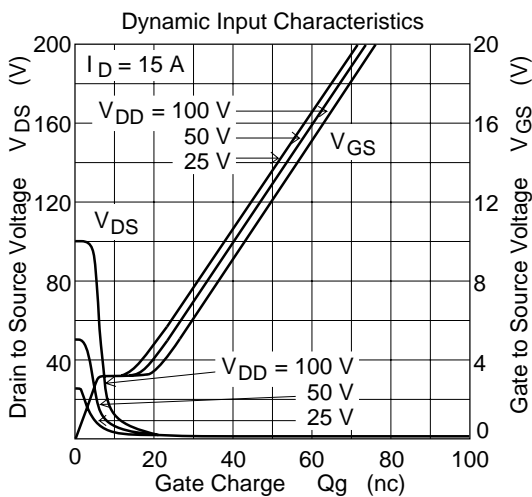
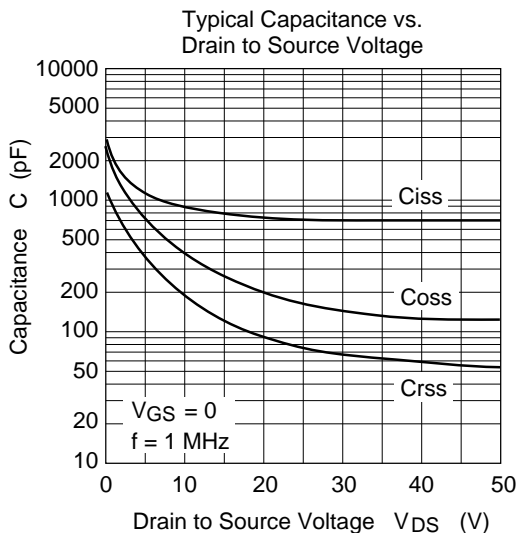
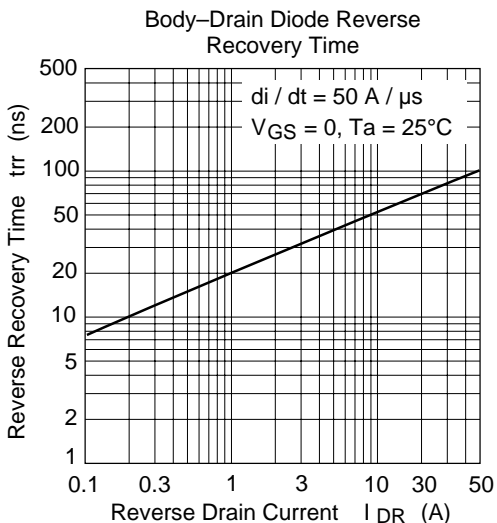
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	100	—	—	V	$I_D = 10 \text{ mA}$ , $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	$\pm 20$	—	—	V	$I_G = \pm 100 \mu A$ , $V_{DS} = 0$
Gate to source leak current	$I_{GSS}$	—	—	$\pm 10$	$\mu A$	$V_{GS} = \pm 16 \text{ V}$ , $V_{DS} = 0$
Zero gate voltage drain current	$I_{DSS}$	—	—	10	$\mu A$	$V_{DS} = 100 \text{ V}$ , $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.5	V	$I_D = 1 \text{ mA}$ , $V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	—	45	60	m $\Omega$	$I_D = 10 \text{ A}$ , $V_{GS} = 10 \text{ V}$ <sup>Note4</sup>
	$R_{DS(on)}$	—	65	85	m $\Omega$	$I_D = 10 \text{ A}$ , $V_{GS} = 4 \text{ V}$ <sup>Note4</sup>
Forward transfer admittance	$ y_{fs} $	8.5	15	—	S	$I_D = 10 \text{ A}$ , $V_{DS} = 10 \text{ V}$ <sup>Note4</sup>
Input capacitance	$C_{iss}$	—	900	—	pF	$V_{DS} = 10 \text{ V}$
Output capacitance	$C_{oss}$	—	400	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	$C_{rss}$	—	210	—	pF	$f = 1 \text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	15	—	ns	$I_D = 10 \text{ A}$ , $V_{GS} = 10 \text{ V}$
Rise time	$t_r$	—	120	—	ns	$R_L = 3 \Omega$
Turn-off delay time	$t_{d(off)}$	—	200	—	ns	
Fall time	$t_f$	—	150	—	ns	
Body-drain diode forward voltage	$V_{DF}$	—	0.9	—	V	$I_F = 20 \text{ A}$ , $V_{GS} = 0$
Body-drain diode reverse recovery time	$t_{rr}$	—	90	—	ns	$I_F = 20 \text{ A}$ , $V_{GS} = 0$ $diF/dt = 50A/\mu s$

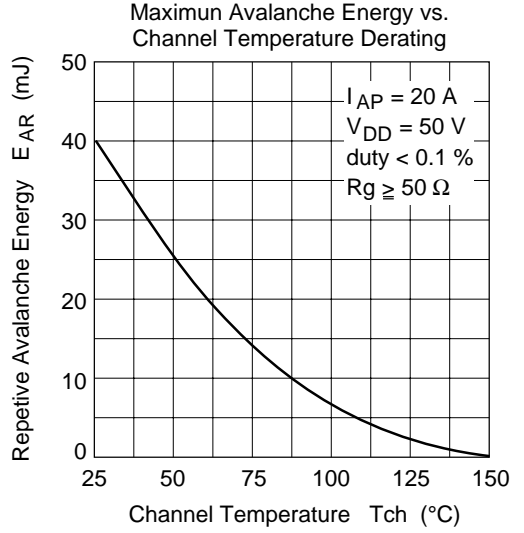
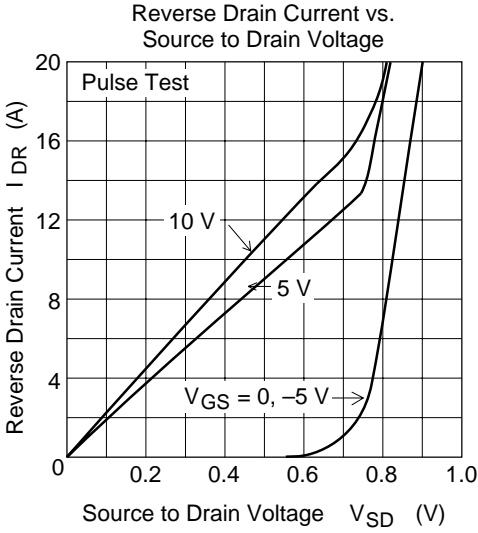
- Note: 4. Pulse test

Main Characteristics

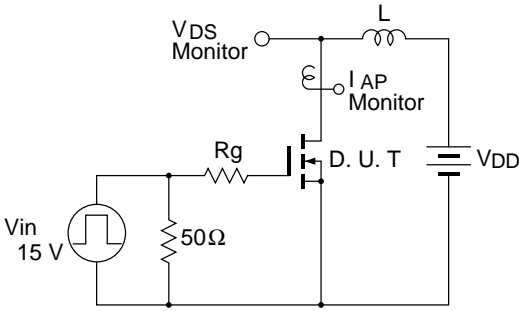






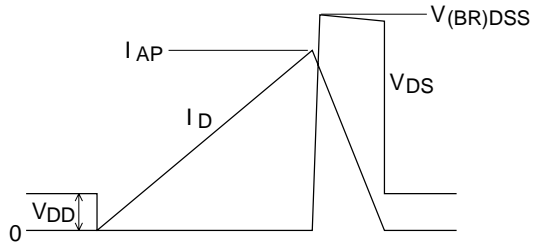


Avalanche Test Circuit

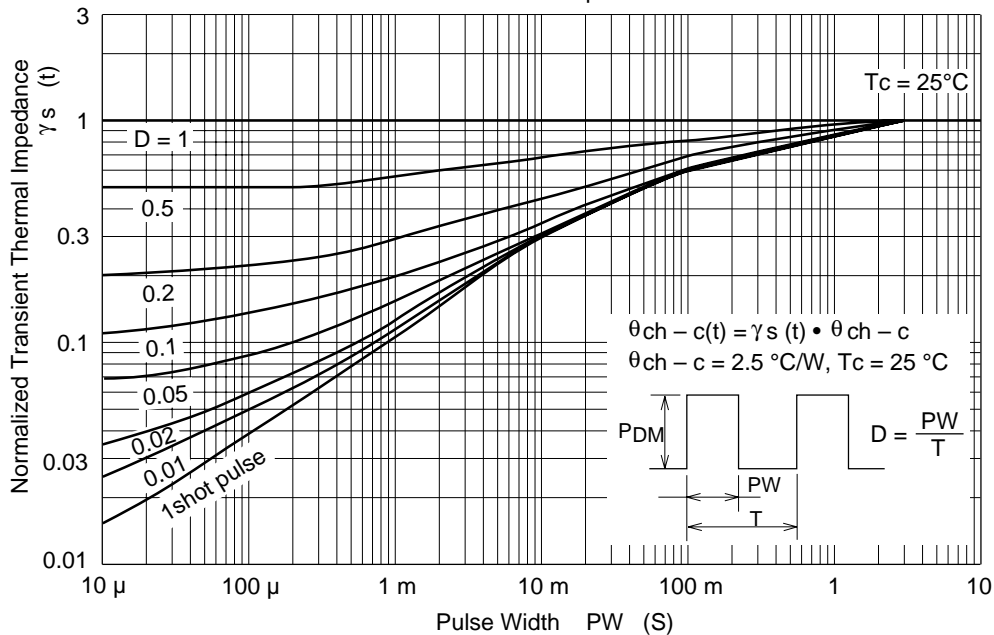


Avalanche Waveform

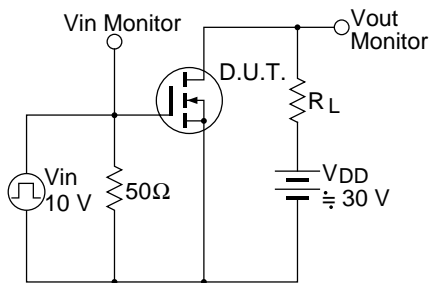
$$E_{AR} = \frac{1}{2} \cdot L \cdot I_{AP}^2 \cdot \frac{V_{DSS}}{V_{DSS} - V_{DD}}$$



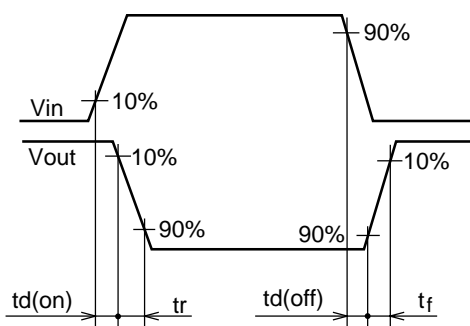
Normalized Transient Thermal Impedance vs. Pulse Width



Switching Time Test Circuit



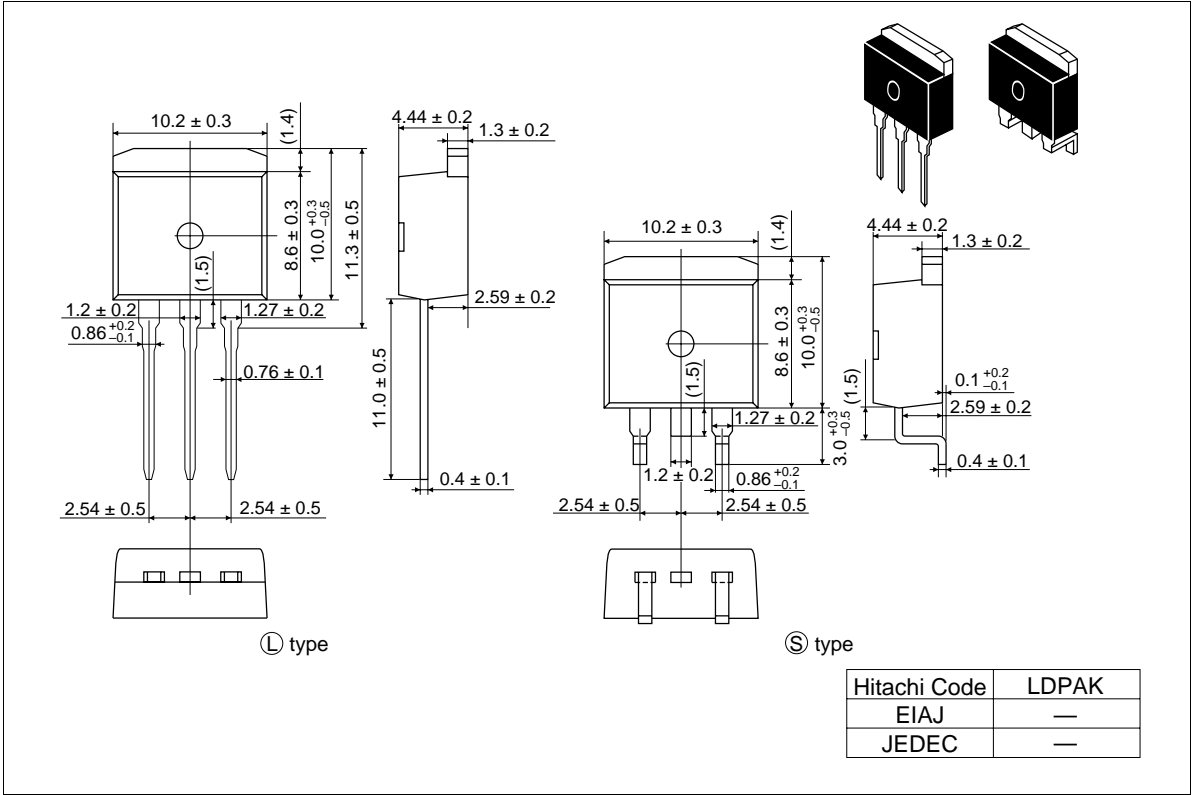
Waveform



# 2SK3150(L),2SK3150(S)

## Package Dimensions

Unit: mm





## Cautions

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